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Communications Solutions
RF Engine

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Vice President and General Manager

Never stop thinking

Disclaimer

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Table of Contents

Table of Contents

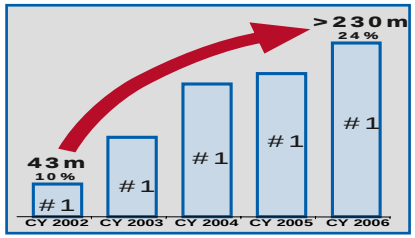
Extended Market Leadership for Infineon's RF Engine Products

COM RF Latest Highlights

Miniaturization

SMARTi PM+ world's smallest EDGE Transceiver (RF Engine <100 mm²)

Volume

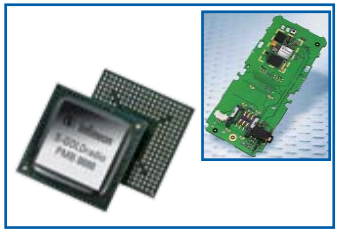


#1 with more than 230 million transceivers shipped in CY 2006

Multimode

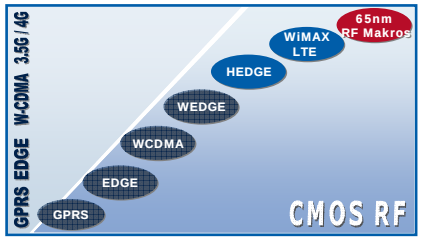
SMARTi UE world's first single-chip HEDGE transceiver with DigRF

BB+RF integration



E-GOLDvoice in production and S-GOLDradio world's first EDGE single-chip

CMOS leadership



Complete TRx portfolio in CMOS RF

Emerging standards

Sampling of SMARTi transceivers for WiMAX and LTE

COM RF Product Portfolio at a Glance

SMARTi® Transceivers

- Comprehensive portfolio: GPRS, EDGE, 3G, multi-mode
- Standard products and customized solutions
- Innovation for:
  - Integration
  - Miniaturization
  - Cost reduction

RF Systems and Engines

- Complete RF Engines and reference designs
- Third party management with all leading RF frontend suppliers

BAW Filter

- Over 200 million BAW filters shipped
- CDMA / WCDMA duplexer
- Interstage filter
- GSM filter
- GPS filter

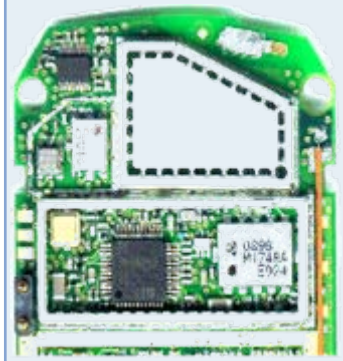
Emerging Standards

- WiMAX 802.16e transceiver
- LTE transceiver and architecture

3GLTE 4G

WiMAX FORUM

Infineon's Track Record in First-to-Market Cellular Transceivers



1999

SMARTi
GSM Dual Band
770 mm²
150 comp.
BoM ~ EUR 14

SMARTi®
First single-chip GSM with integrated VCO/PLL

SMARTi+
First single-chip 3-band GPRS TRx;

SMARTi SD
First single-chip CMOS GPRS TRx

SMARTi U
First single-chip W-CDMA TRx

SMARTi PM
First CMOS single-chip EDGE

SMARTi 3G
First CMOS single-chip WCDMA

SMARTi 3GE
First CMOS dual-mode WEDGE TRx

SMARTi UE
First CMOS DigRF HEDGE

SMARTi PM+
smallest EDGE TRx

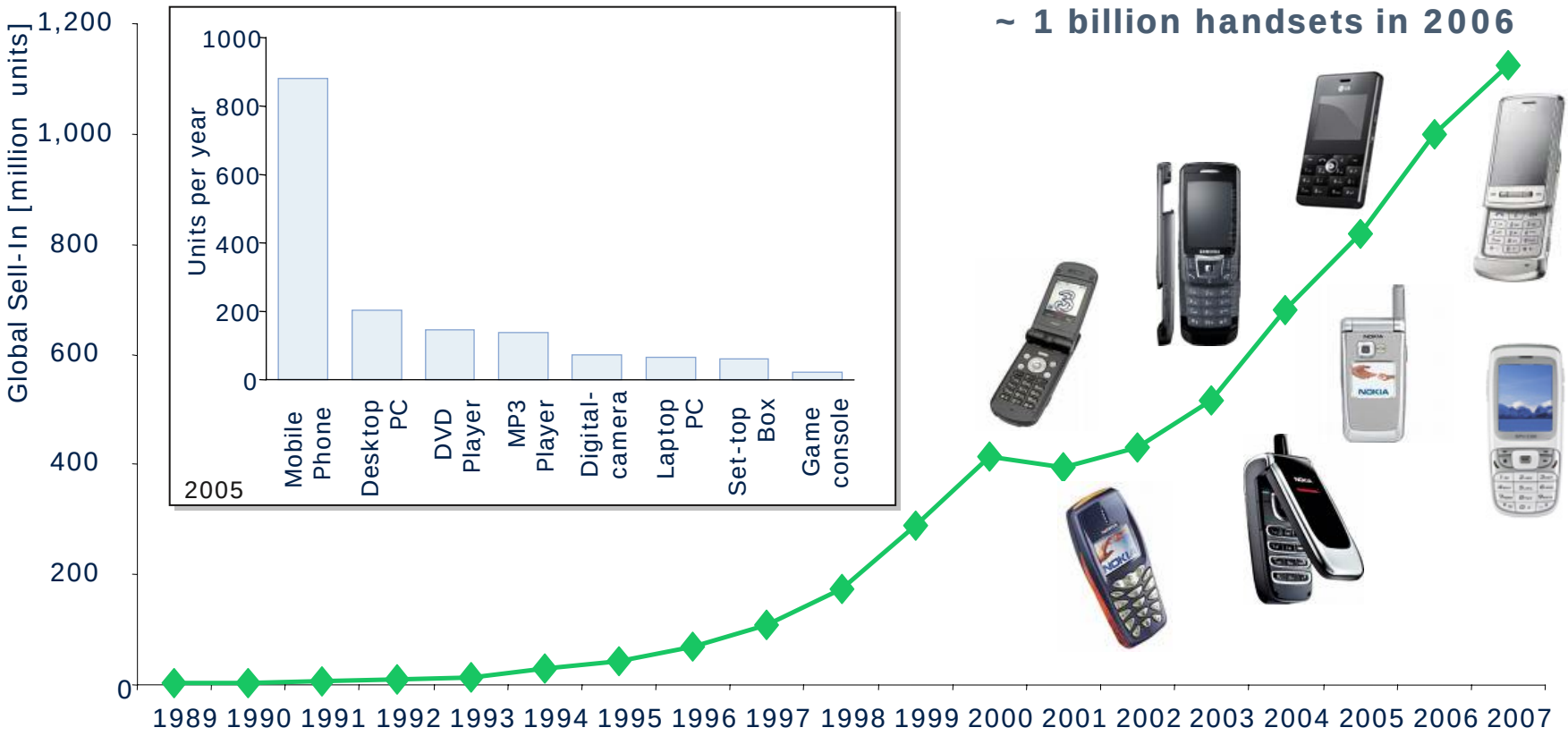
1999 2000 2003 2005 2006 2007

2007

SMARTi PM+
GSM/GPRS/EDGE
Quad Band
100 mm²
20 components
BoM < EUR 3

Table of Contents

The World's Largest Electronic Consumer Market



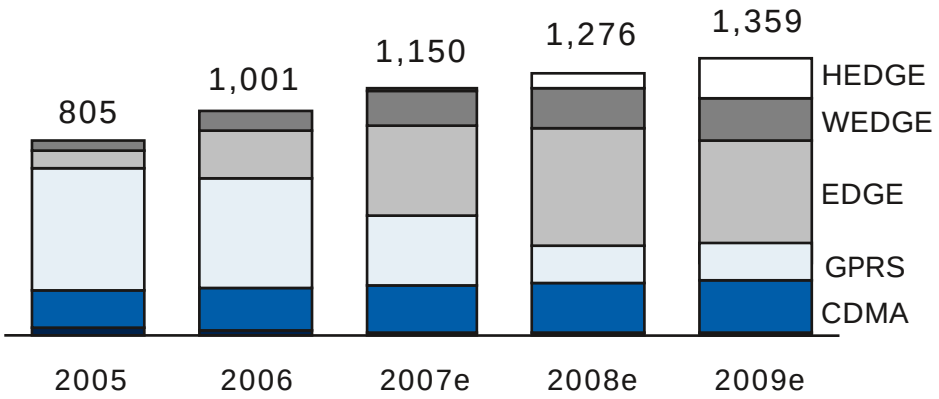
- Mobile phone market is expected to continue its growth path with a CAGR of 8.0% from 2006 to 2010.
- Drivers are new subscribers (ULC) and replacements (EDGE and 3G).

Source: ABI, Research, Strategy Analytics

Multi-mode Operation, High-volumes and Fast Design Cycles are the Challenges for RF

Market development

Worldwide mobile phone shipments by air interface [m units]



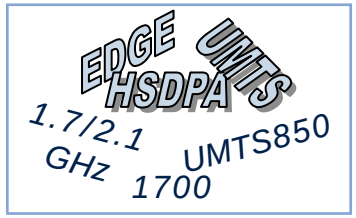
- 3G phones to grow from 52 million in 2005 to 304 million in 2009.
- EDGE phones to grow from 14 million in 2005 to more than 600 million in 2009.

Source: ABI Research, 2006

RF requirements

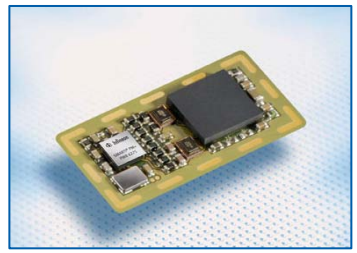
From GSM to Multimode

- More standards
- Multiple bands
- Optimized power consumption



Ease of implementation

- Miniaturization and integration
- Fast time-to-market
- Standard digital interfaces - DigRF

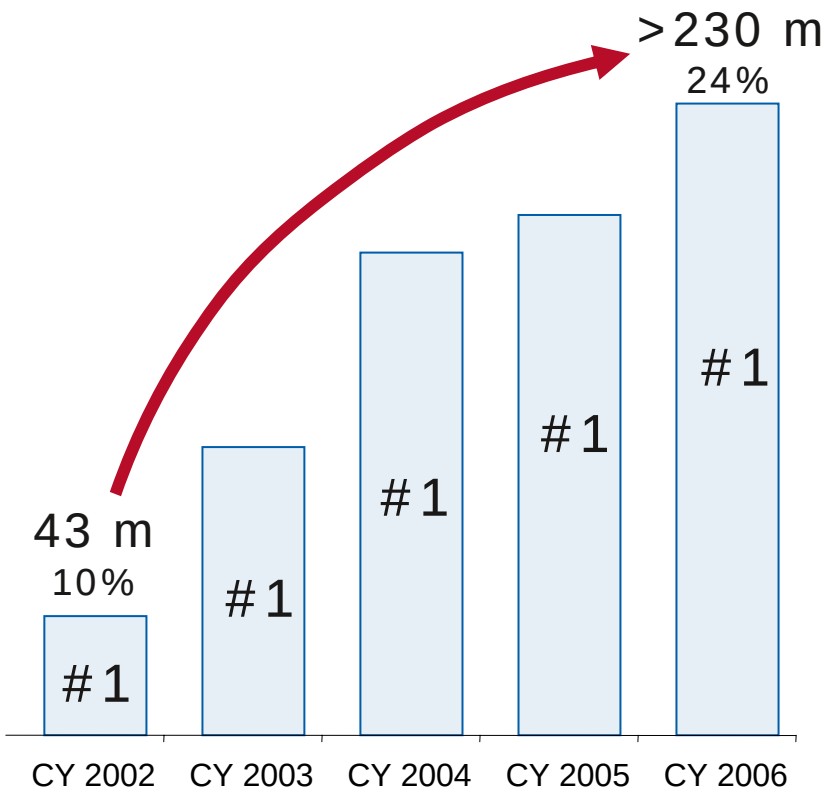


High Volume

- Best cost position
- Secure and flexible supply

Infineon RF Transceivers for Cellular Applications - Steady Growth of Market Share

IFX market share and ranking in RF transceivers



Major Contributors

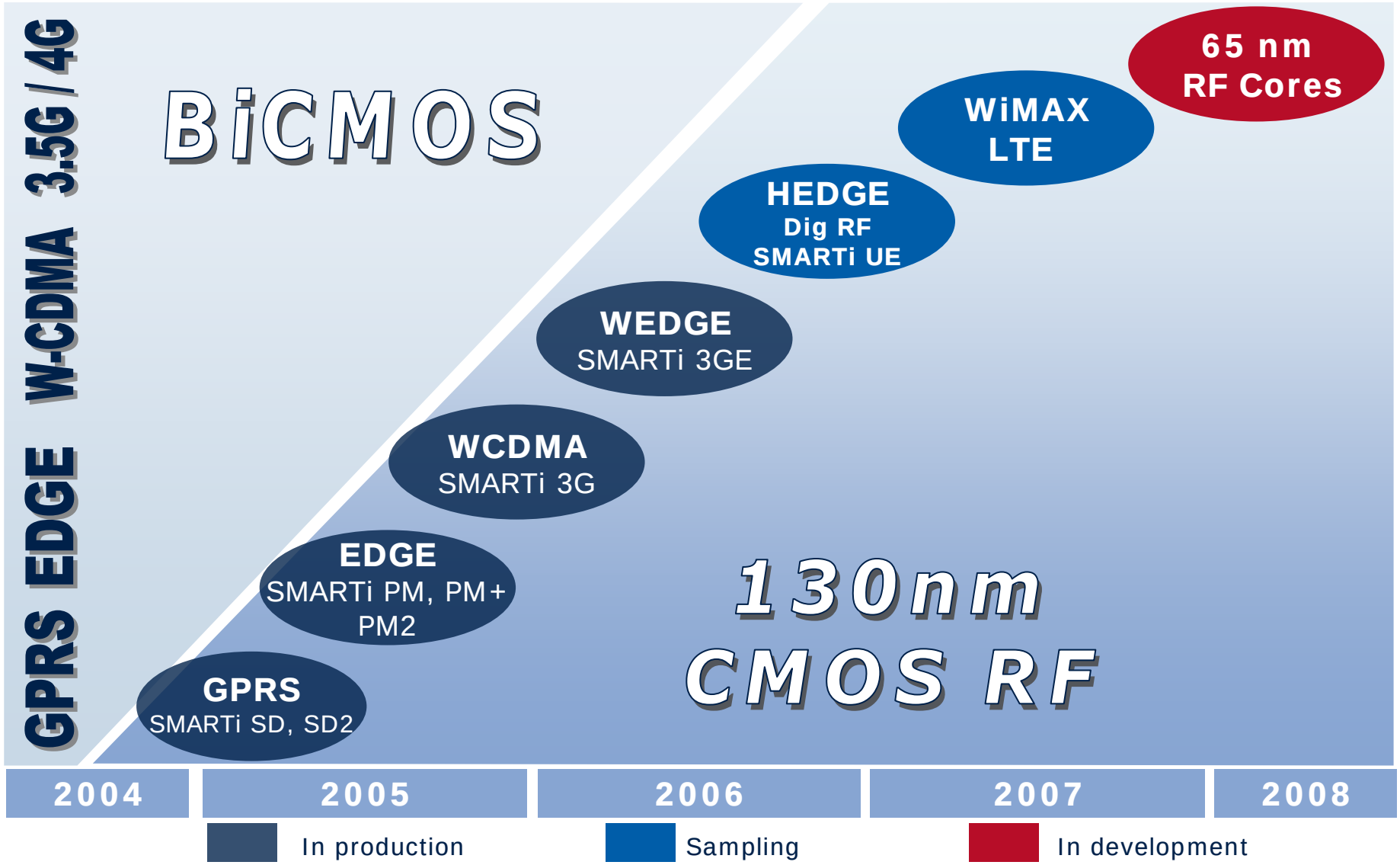
- Successful ramp-up of new RF transceivers for major OEMs.
- CMOS transceiver in volume production since 2004.
- Complete product and roadmap conversion to CMOS technology.
- Leading cost position.
- Excellent RF performance.

→ By end of CY 2007 we will have shipped 1 billion cellular transceivers

Source: Gartner, Strategy Analytics; IFX

Table of Contents

Comprehensive CMOS RF Transceiver Portfolio: All Wireless Standards in Single CMOS Technology



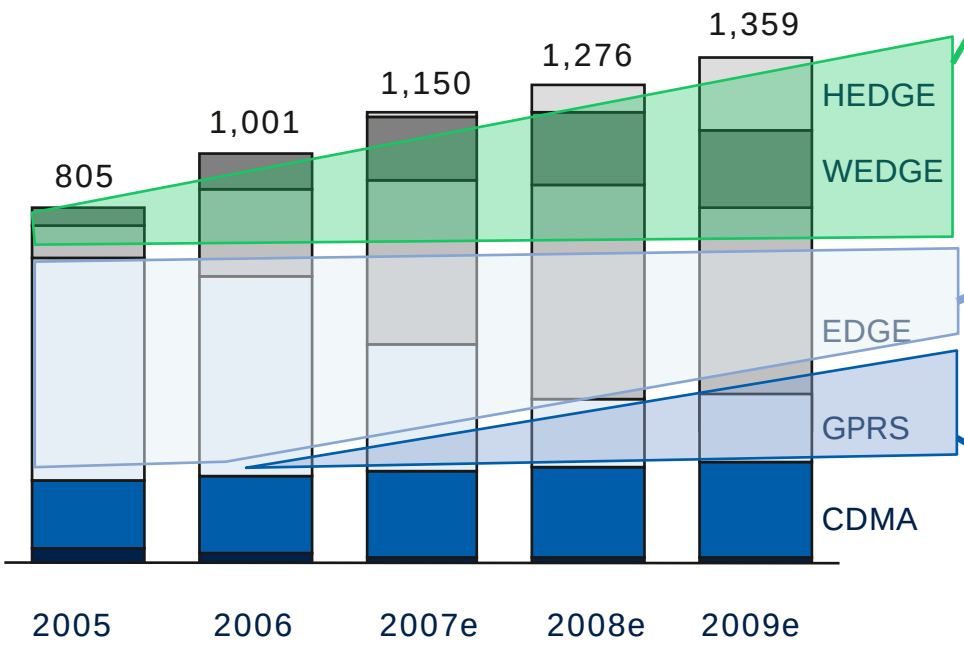
Infineon's RF Offering For the Different Requirements of the 3 Cellular Market Segments

Market Segment / Trend	IFX Product
3G / 4G Multimode ■ Multi-band transceivers (up to 7 bands). ■ Multi-mode solutions (UMTS + EDGE + GPRS). ■ Digital RF-to-Baseband interfaces. ■ Increasing demand for HSDPA/HSUPA and diversity solutions.	
2.5G EDGE ■ Cost effective EDGE transceivers. ■ High Volume: gaining ~ 40% of cellular market by 2008. ■ Trend towards ultra-small RF systems and digital BB/RF interface.	
2G GSM/GPRS ■ Commodity business. ■ Lowest customer cost of ownership. ■ Trend towards monolithic integration of RF and BB.	

Stand-alone TRx and Scalable BB Solutions Driven by 3G Multi-mode and High Tier EDGE

RF Market Segmentation

Worldwide mobile phone shipments by air interface [m units]



Innovative RF Engines
- Stand alone transceiver solutions
- Multi-bands, multi-mode
- Size and power consumption critical
- Growing volume
- High innovation
- High ASP (x3-x5 of GSM/GPRS)

Commoditized RF Engines
- Stand-alone transceiver solutions
- High volume
- Cost competitive market

Integrated RF+BB Solutions
- Baseband + RF Integration
- Handsets with fixed feature set
- Commodity
- Ultra-low cost

Source: ABI Research, 2006; IFX

SMARTi PM Enables Best Performing and Most Cost-effective EDGE RF Solutions

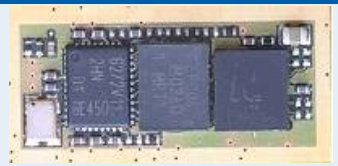
Competitor‘s EDGE solution shipping today

Front side

Back side

- 55 components
- double side PCB
- ~ 310 mm²

Infineon‘s EDGE solution shipping today



- **20** components
- **single** side PCB
- **~170 mm²**

- Smaller form factor ✓
- Lower customer cost of ownership ✓
- Excellent, stable performance ✓

*Not drawn to scale

SMARTi PM track record

SGH-D900

SGH-E898

KE850

Startrek
Orange
“SPV F600”,
Cingular3125

KE820

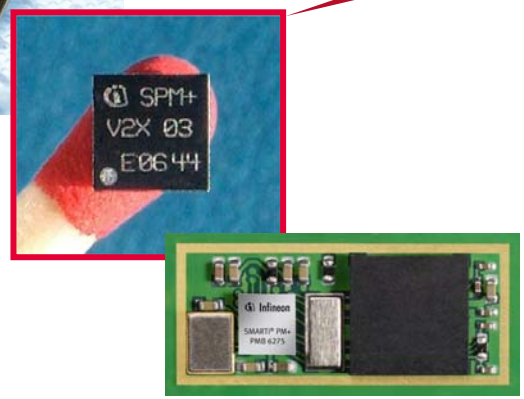
T-Mobile
DASH

Softbank
705P/706P

Based on the Success of SMARTi PM the SMARTi PM+ Sets New Standards for Miniaturization

SMARTi PM+

The world‘s smallest EDGE transceiver



World‘s smallest EDGE solution

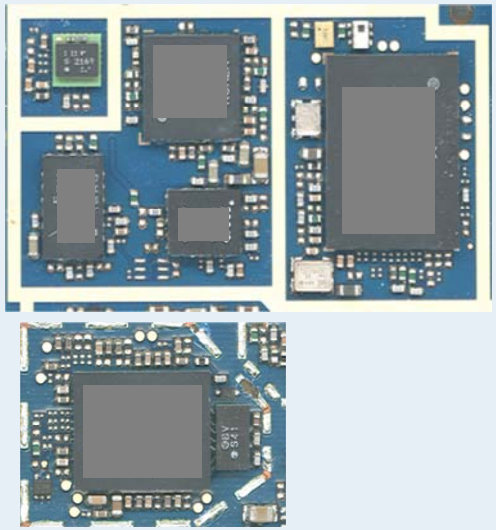
New design-wins at two tier-1 OEMs

- **Smallest footprint: 3x3 mm²**
- **Lowest height: < 1.0 mm**
- **Micro Radio solution < 100 mm²**
- **Ramp-up in 2nd half 2007**

SMARTi 3G and SMARTi 3GE Underline Infineon's Leadership in 3G RF

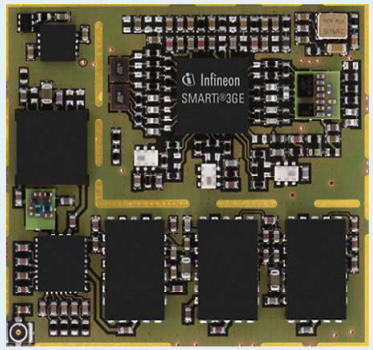
Competitor

- Dual-band UMTS
- Triple-band EDGE
- 3.2M/s HSDPA
- PCB size: 1162 mm²



SMARTi 3GE

- Triple-band UMTS
- Quad-band EDGE
- 7.2M/s HSDPA
- PCB size: 800 mm²



Multi-band world platform

- -30% components ✓
- -30% footprint ✓
- -30% eBOM ✓

SMARTi 3GE / 3G track record

SMARTi 3G

SMARTi 3GE

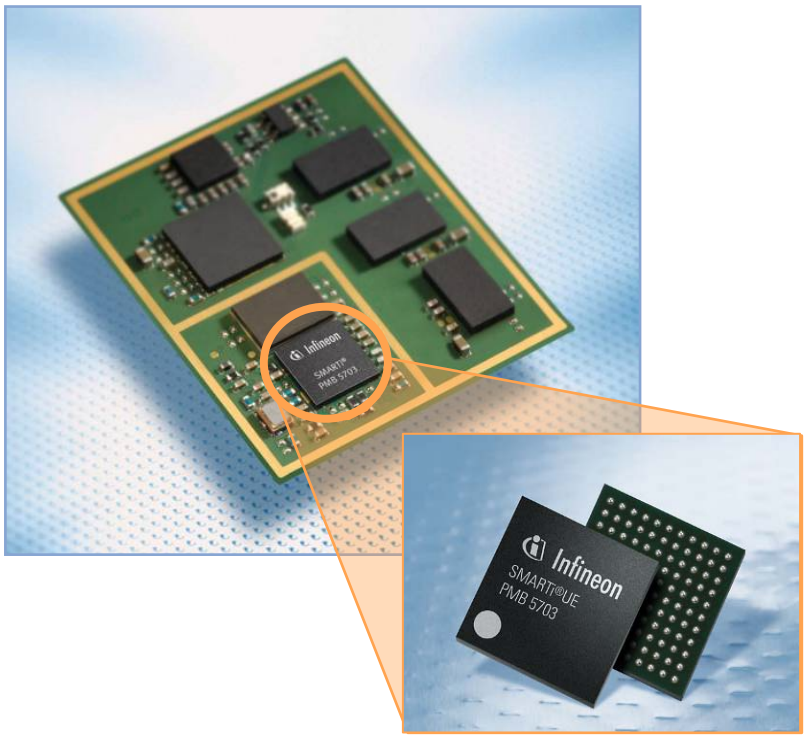
Ramp-up with 3 tier-1 OEMs in 2007

Both Chipsets recently in production

SMARTi UE is the New Benchmark for Multi-mode 3.5G Cellular RF Transceivers

SMARTi UE

The new benchmark in cellular RF



- **More than 50% reduction of RF PCB area (< 400 mm²).**
- **Lowest component count (< 50 components).**
- **Integrated analog baseband**
- **Embedded µController enabling simplified programming and fastest factory calibration.**
- **Covering all UMTS bands worldwide.**
- **Interoperable with all DigRF Basebands.**

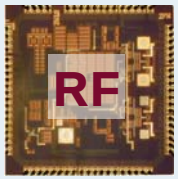
World's first single-chip HEDGE RF transceiver with DigRF baseband interface

New design-win at tier-1 OEM

65 nm CMOS Solutions Will Pave the Way for Cost, Size and Performance Improvements in '08

2003

Stand-alone transceiver

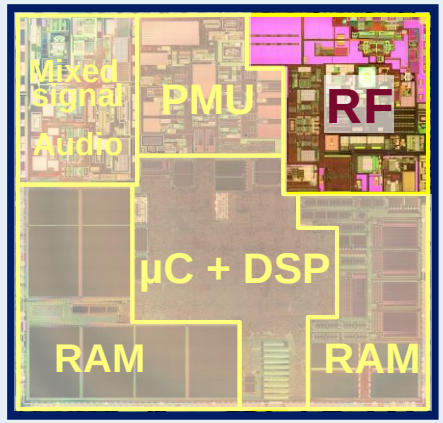


130 nm RF CMOS

Infineon is the leading company in RF CMOS design

2006

Baseband with integrated RF



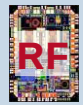
130 nm RF CMOS

Infineon is the leading company in baseband + RF integration

2008

RF transceiver cores for stand alone TRx and leading BB/radios

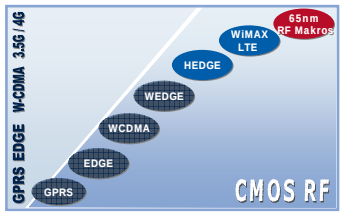
65 nm CMOS



- 95% digital signal processing in receive path
- Fully digital transmit path
- No compromises in RF performance
- Plain vanilla CMOS technology

Table of Contents

Infineon's Cellular Transceiver Products: What Differentiates Us From Competition



System Expertise
-Complete Reference Systems
- Platforms:
BB + RF + SW

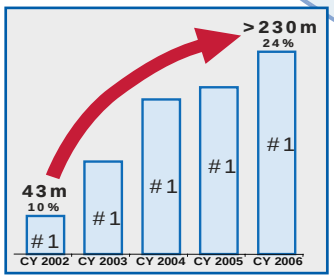
Product Portfolio
- Comprehensive product portfolio for 2.5G, 3G and LTE
- Strong IP and patent portfolio

Best in Class Performance
- Sensitivity
- Modulation spectrum
- EVM

Lowest Customer Cost of Ownership
-CMOS technology
- Robustness in production
- Lowest eBOM
Monolithic integration

Security of Supply
- IFX own fab cluster
- CMOS technology

Track Record
- Market leader for Transceiver
- Supplying major OEMs and ODM



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Never stop thinking

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